PART INFORMATION	
Mfg Item Number	MPC8536EAVTAQG
Mfg Item Name	FCPBGA 783 29SQ2.9P1.0

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2016-11-08
Response Document ID	8446K11256D048A1.26
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e2
EU RoHS Exemption(s)	15

MANUFACTURING	
Mfg Item Number	MPC8536EAVTAQG
Mfg Item Name	FCPBGA 783 29SQ2.9P1.0
Version	ALL
Weight	3.695600
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	15:Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
	6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c) : Copper alloy containing up to 4% lead by weight
	7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Capacitor, 0306	0.0782						g					
Capacitor, 0306		Metals	Copper, metal	7440-50-8		0.0107916	g	138000	13.8		2920	0.292
Capacitor, 0306		Nickel (external applications only)	Nickel	7440-02-0		0.015249	g	195000	19.5		4126	0.4126
Capacitor, 0306		Metals	Tin, metal	7440-31-5		0.0010166	g	13000	1.3		275	0.0275
Capacitor, 0306		Metals	Barium titanate	12047-27-7		0.0511428	g	654000	65.4		13838	1.3838
Capacitor Solder Paste	0.0065						g					
Capacitor Solder Paste		Solvents, additives, and other materials	Other aliphatic amines	-		0.00001365	g	2100	0.21		3	0.0003
Capacitor Solder Paste		Metals	Aluminum, metal	7429-90-5		0.00000007	g	10	0.001		0	0
Capacitor Solder Paste		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.0000065	g	1000	0.1		1	0.0001
Capacitor Solder Paste		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000064	g	99	0.0099		0	0
Capacitor Solder Paste		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00000195	g	300	0.03		0	0
Capacitor Solder Paste		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0.00000013	g	20	0.002		0	0
Capacitor Solder Paste		Metals	Copper, metal	7440-50-8		0.00003179	g	4890	0.489		8	0.0008
Capacitor Solder Paste		Metals	Gold, metal	7440-57-5		0.00000033	g	50	0.005		0	0
Capacitor Solder Paste		Metals	Iron, metal	7439-89-6		0.0000013	g	200	0.02		0	0
Capacitor Solder Paste		Lead/Lead Compounds	Lead	7439-92-1		0.00000325	g	500	0.05		0	0
Capacitor Solder Paste		Nickel (external applications only)	Nickel	7440-02-0		0.00000065	g	100	0.01		0	0
Capacitor Solder Paste		Metals	Silver, metal	7440-22-4		0.00017453	g	26850	2.685		47	0.0047
Capacitor Solder Paste		Metals	Tin, metal	7440-31-5		0.00626384	g	963670	96.367		1694	0.1694
Capacitor Solder Paste		Metals	Zinc, metal	7440-66-6		0.00000137	g	211	0.0211		0	0
Solder Balls - Pb Free, Sn/Ag	0.6385						g					
Solder Balls - Pb Free, Sn/Ag		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.00060721	g	951	0.0951		164	0.0164
Solder Balls - Pb Free, Sn/Ag		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00005555	g	87	0.0087		15	0.0015
Solder Balls - Pb Free, Sn/Ag		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.0002554	g	400	0.04		69	0.0069
Solder Balls - Pb Free, Sn/Ag		Metals	Iron, metal	7439-89-6		0.00022348	g	350	0.035		60	0.006
Solder Balls - Pb Free, Sn/Ag		Lead/Lead Compounds	Lead	7439-92-1		0.00001469	g	23	0.0023		3	0.0003
Solder Balls - Pb Free, Sn/Ag		Metals	Silver, metal	7440-22-4		0.02236921	g	35034	3.5034		6052	0.6052
Solder Balls - Pb Free, Sn/Ag		Metals	Tin, metal	7440-31-5		0.61497446	g	963155	96.3155		166407	16.6407
Organic Substrate, Halogen-fre	2.5643				15		g					
Organic Substrate, Halogen-fre		Metals	Copper, metal	7440-50-8		0.99715626	g	388861	38.8861		269841	26.9841
Organic Substrate, Halogen-fre		Plastics/polymers	Other Epoxy resins	-		0.76215099	g	297216	29.7216		206232	20.6232
Organic Substrate, Halogen-fre		Lead/Lead Compounds	Lead	7439-92-1		0.00101803	g	397	0.0397		275	0.0275
Organic Substrate, Halogen-fre		Glass	Fiberglass	-		0.71933231	g	280518	28.0518		194645	19.4645
Organic Substrate, Halogen-fre		Glass	Other silica compounds	-		0.06702054	g	26136	2.6136		18135	1.8135
Organic Substrate, Halogen-fre		Metals	Silver, metal	7440-22-4		0.00007949	g	31	0.0031		21	0.0021
Organic Substrate, Halogen-fre		Metals	Tin, metal	7440-31-5		0.01754238	g	6841	0.6841		4746	0.4746
High Pb Bumped Semiconductor D	0.3463				15		g					
High Pb Bumped Semiconductor D		Lead/Lead Compounds	Lead	7439-92-1		0.0326135	g	94177	9.4177		8824	0.8824
High Pb Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.0002857	g	825	0.0825		77	0.0077
High Pb Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.00171626	g	4956	0.4956		464	0.0464
High Pb Bumped Semiconductor D		Metals	Titanium, metal	7440-32-6		0.00001454	g	42	0.0042		3	0.0003
High Pb Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.0031167	g	9000	0.9		843	0.0843
High Pb Bumped Semiconductor D		Glass	Silicon, doped	-		0.3085533	g	891000	89.1		83492	8.3492
Underfill	0.0618						g					
Underfill		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.010506	g	170000	17		2842	0.2842
Underfill		Glass	Silicon dioxide	7631-86-9		0.04017	g	650000	65		10869	1.0869
Underfill		Glass	Proprietary Material-Other silica compounds	-		0.004944	g	80000	8		1337	0.1337
Underfill		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.00618	g	100000	10		1672	0.1672

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPC8536EAVTAQG_IPC1752_v11.xml

http://www.freescale.com/mcds/MPC8536EAVTAQG_IPC1752A.xml